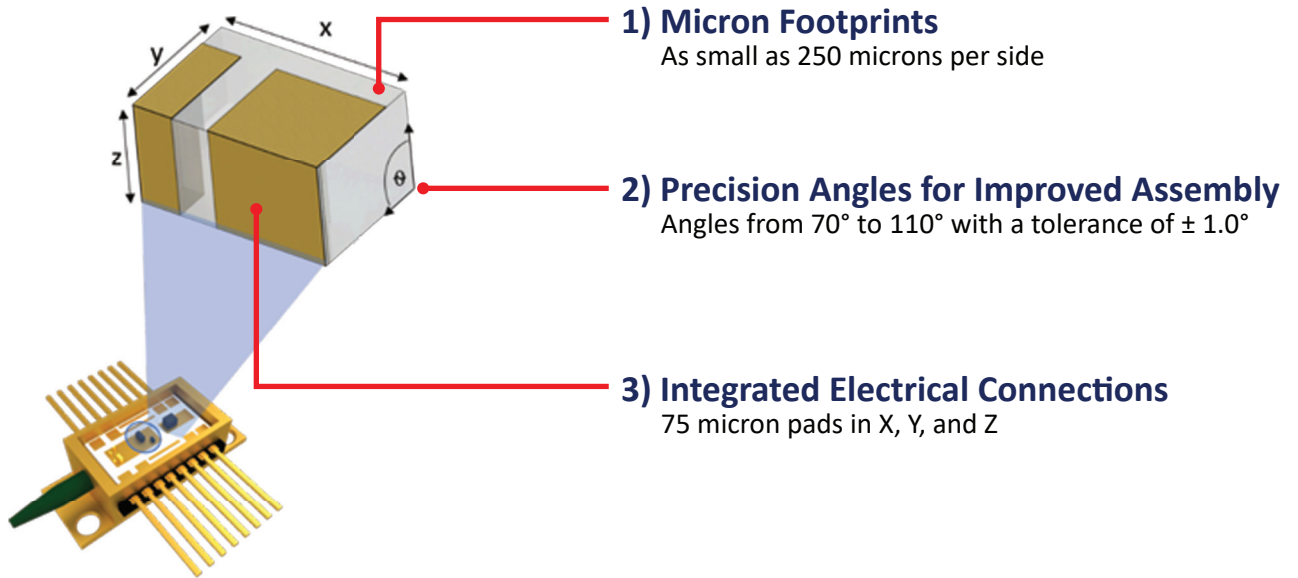


LASER SUBMOUNTS

EDGE WRAPS

Improve and Simplify Integration

High-density arrays simplify integration, alignment, and assembly, speeding up manufacturing and reducing BOM.



Improve Performance and Reduce Package Size

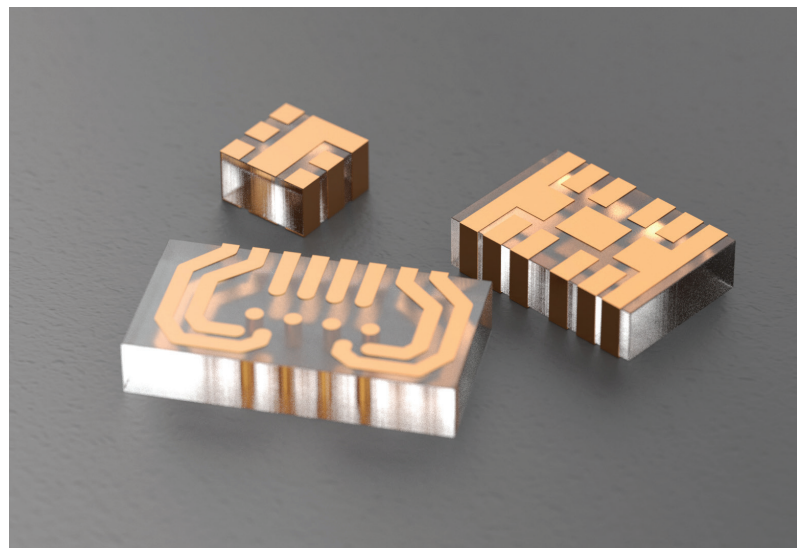
The high-density arrays simplify integration, alignment, and assembly. High-accuracy alignments reduce assembly errors and improve assembly costs.

High-Volume Manufacturing

Wafer-level production ensures high-volume production with run-to-run repeatability.

Precision Manufacturing

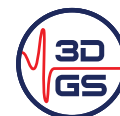
3DGS manufacturing process ensures the accurate manufacturing of edge wraps and alignment features with micro-scale precision every time!



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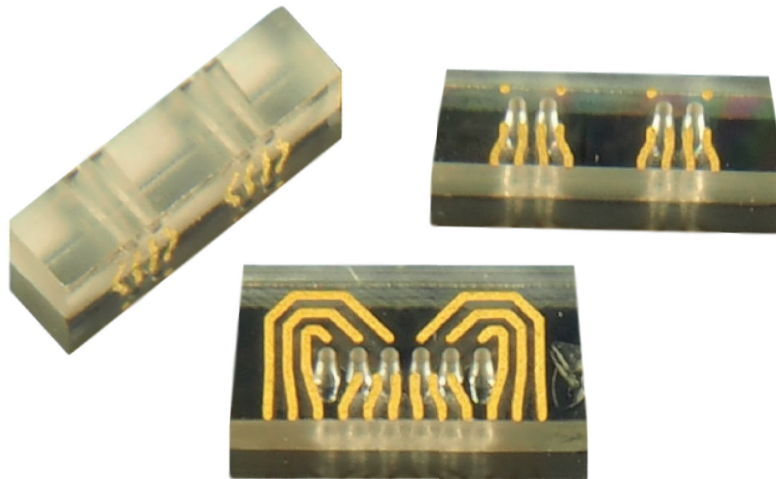
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Enabling the GHz Generation

LASER SUBMOUNTS

EDGE WRAPS



Electrical and Optical Integration

Electrical traces can be combined with through-holes or edge wraps to maximize integration possibilities, further reducing package sizes.

Custom Solutions for Improved Outcomes

Each application is unique in footprint, thermal management requirements, and additional features. Contact us directly with your specific needs.

Design Limits

PARAMETERS	TYPICAL	PERFORMANCE LIMITS
Size	0.75 mm x 0.75 mm	0.25 mm x 0.35 mm
Height	0.35 mm	0.10 mm
Angular Tolerances	70° to 110°, ± 1.5°	70° to 110°, ± 1.0°
Pad Width	100 µm to 500 µm	75 µm to 500 µm
Spacing Between Pads	100 µm	75 µm
Thermal Capacity	1 W/mK	50 W/mK
Assembly Options	Solder, wire bond	Solder, wire bond



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